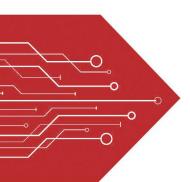
# MSKSEMI















**ESD** 

TVS

TSS

MOV

GDT

**PLED** 

# Broduct data sheet



SOD-323



#### **FEATURES**

- Low Turn-on Voltage
- Fast Switching
- PN Junction Guard for Transient and ESD Protection
- Designed for Surface Mount Application
- Plastic Material –UL Recognition Flammability Classification 94V-O

**MARKING: K73** 



Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25

<u> </u>		<u> </u>	
Parameter	Symbol	Limit	Unit
Peak Repetitive Peak Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	70	V
DC Blocking Voltage	$V_R$		
Forward Continuous Current	I <sub>F</sub>	70	mA
Bcb!fYdYfjrjj YPeak Forward Surge Current '4 hl, " a g	I <sub>FSM</sub>	100	mA
Power Dissipation	PD	200	mW
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	500	°C/W
Operating Junction Temperature Range	TJ	-40 ~ +125	℃
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	$^{\circ}$

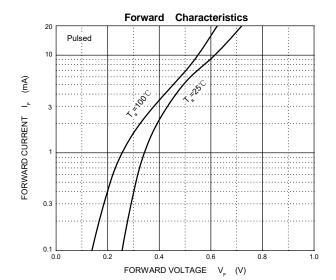
#### Electrical Ratings @Ta=25℃

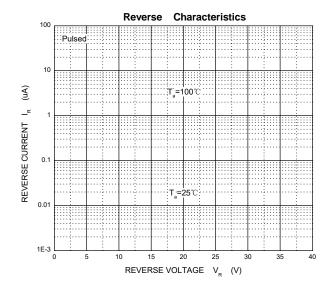
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Forward voltogo	V <sub>F1</sub>			0.41	V	I <sub>F</sub> =1mA
Forward voltage	V <sub>F2</sub>			1	V	I <sub>F</sub> =15mA
Reverse current	I <sub>R</sub>			100	nA	V <sub>R</sub> =50V
Capacitance between terminals	Ст			2	pF	V <sub>R</sub> =0V,f=1MHz
Payarsa racayary tima	t <sub>rr</sub>			5	ns	I <sub>F</sub> =I <sub>R</sub> =10mA
Reverse recovery time						Irr=0.1 $XI_R$ , $R_L$ =100 $\Omega$

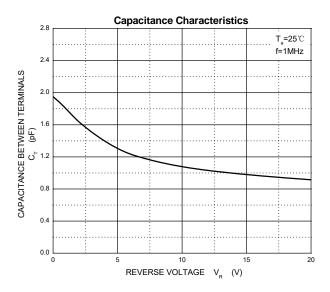


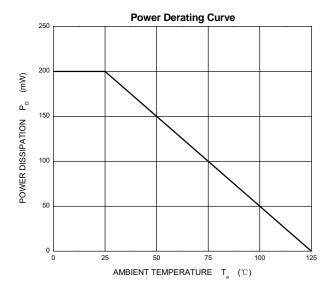
Semiconductor





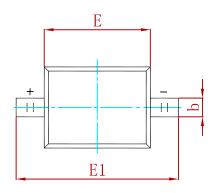


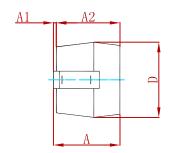


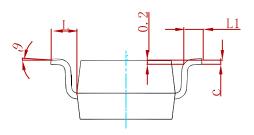




### PACKAGE MECHANICAL DATA

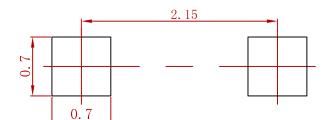






Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.000		0.039	
A 1	0.000	0.100	0.000	0.004	
A2	0.800	0.900	0.031	0.035	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	1.200	1.400	0.047	0.055	
E	1.600	1.800	0.063	0.071	
E1	2.550	2.750	0.100	0.108	
L	0.475	REF.	0.019	REF.	
L1	0.250	0.400	0.010	0.016	
θ	0°	8°	0°	8°	

# **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
BAS70WS	SOD-323	3000



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